

Plastic Packages for Integrated Circuits

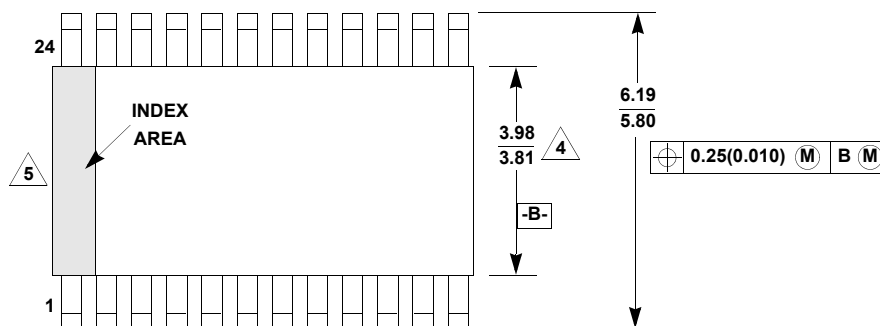
Package Outline Drawing

M24.15

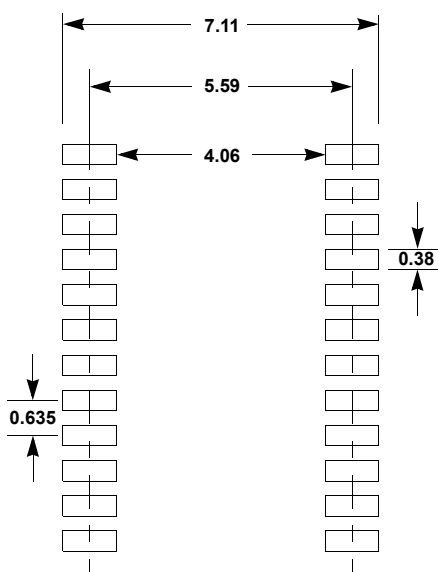
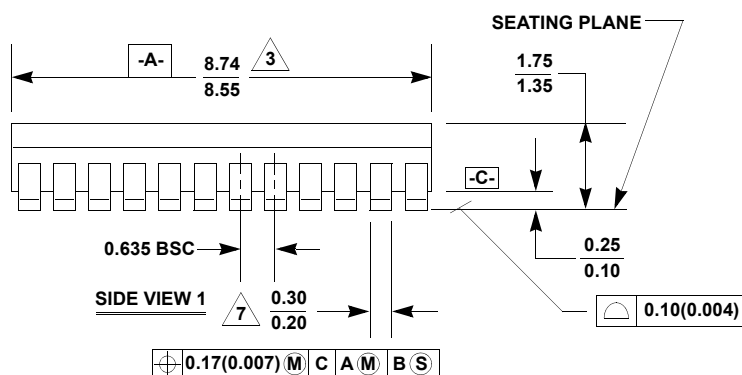
24 LEAD SHRINK SMALL OUTLINE PLASTIC PACKAGE (QSOP/SSOP)

0.150" WIDE BODY

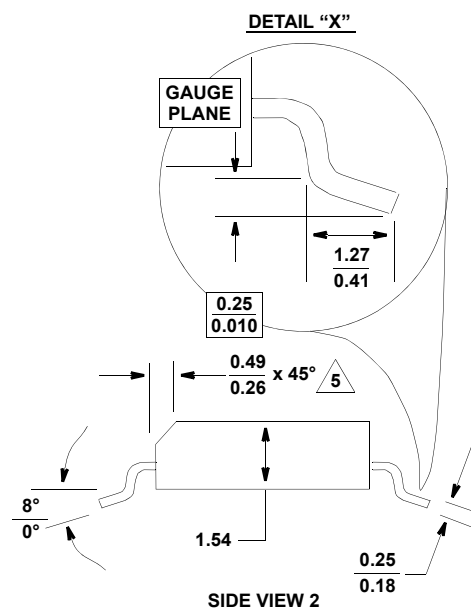
Rev 3, 2/13



TOP VIEW



TYPICAL RECOMMENDED LAND PATTERN



NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Package length does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Package width does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. Terminal numbers are shown for reference only.
7. Lead width does not include dambar protrusion. Allowable dambar protrusion shall be 0.10mm (0.004 inch) total in excess of "B" dimension at maximum material condition.
8. Controlling dimension: MILLIMETER.